



Product End-of-Life Disassembly Instructions

Product Category: Networking Equipment

Marketing Name / Model

[List multiple models if applicable.]

HP HSR6808 Router Chassis (JG363A)

Purpose: The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HP products to remove components and materials requiring selective treatment, as defined by EU directive 2002/96/EC, Waste Electrical and Electronic Equipment (WEEE).

1.0 Items Requiring Selective Treatment

1.1 Items listed below are classified as requiring selective treatment.

1.2 Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.

| Item Description | Notes | Quantity of items included in product |
|--|---|---------------------------------------|
| Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA) | With a surface greater than 10 sq cm | 3 |
| Batteries | All types including standard alkaline and lithium coin or button style batteries | 0 |
| Mercury-containing components | For example, mercury in lamps, display backlights, scanner lamps, switches, batteries | 0 |
| Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm | Includes background illuminated displays with gas discharge lamps | 0 |
| Cathode Ray Tubes (CRT) | | 0 |
| Capacitors / condensers (Containing PCB/PCT) | | 0 |
| Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height | | 0 |
| External electrical cables and cords | | 0 |
| Gas Discharge Lamps | | 0 |
| Plastics containing Brominated Flame Retardants weighing > 25 grams (not including PCBs or PCAs already listed as a separate item above) | | 0 |
| Components and parts containing toner and ink, including liquids, semi-liquids (gel/paste) and toner | Include the cartridges, print heads, tubes, vent chambers, and service stations. | 0 |
| Components and waste containing asbestos | | 0 |
| Components, parts and materials containing refractory ceramic fibers | | 0 |
| Components, parts and materials containing radioactive substances | | 0 |

2.0 Tools Required

List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

| Tool Description | Tool Size (if applicable) |
|------------------|---------------------------|
| Screw driver | 2 # |
| | |

3.0 Product Disassembly Process

3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment:

1. Unscrew the screws on mounting angle 2, and then remove mounting angle 2 from the chassis.
2. Unscrew the screws on front panel 3,4,5, and then remove front panel 3,4,5 from the chassis.
3. Unscrew the screws on blank filler panel 6, and then remove blank filler panel 6 from the chassis.
4. Unscrew the screws on blank filler panel 7, and then remove blank filler panel 7 from the chassis.
5. Unscrew the screws on power module 8, and then remove power module 8 from the chassis.
6. Unscrew the screws on blank power module panel 9, and then remove blank power module panel 9 from the chassis.
7. Remove plastic front panel 10 from the chassis.
8. Unscrew the screws on dustproof frame 11, and then remove dustproof frame 11 from the chassis.
9. Unscrew the screws on wire channel 12, and then remove wire channel 12 from the chassis.
10. Unscrew the screws on fan frame 13, and then remove fan frame 13 from the chassis.
11. Remove film 14 from plastic panel 15.
12. Remove plastic panel 15 from the chassis.
13. Unscrew the screws on back cover 16, and then remove back cover 16 from the chassis.
14. Unscrew the screws on reinforcing bar 17, and then remove reinforcing bar 17 from the chassis.
15. Unscrew the screws on Wire Plate 18, and then remove Wire Plate 18 from the chassis.
16. Unscrew the screws on PCB 19, and then remove PCB 19 from the chassis.
17. Unscrew the screws on PCB 20, and then remove PCB 20 from the chassis.
18. Remove film 21 shielding finger 22 from the chassis.
19. Unscrew the screws on pcb 3-1 and sheet metal 3-2, then remove the pcb 3-1, sheet metal 3-2 from front panel 3-6.
20. Unscrew the screws on guiding set 3-3, then remove guiding set 3-3 from pcb 3-1.
21. Remove shielding finger 3-4 and film 3-5 from front panel 3-6.
22. Unscrew the screws on pcb 4-1, sheet metal 4-2 and heat sink 4-7, then remove them from front panel 4-5.
23. Remove light pipe 4-6 from pcb 4-1.
24. Remove shielding finger 4-3 and film 4-4 from front panel 4-5.
25. Remove conductive foam from 4-8 from front panel 4-5.
26. Unscrew the screws on pcb 5-1 and sheet metal 5-2, then remove the pcb 5-1, sheet metal 5-2 from front panel 5-6.
27. Unscrew the screws on guiding set 5-3, then remove guiding set 5-3 from pcb 5-1.
28. Remove shielding finger 5-4 and film 5-5 from front panel 5-6.
29. Remove shielding finger 6-2 and film 6-3 from blank filler panel 6-1.
30. Remove shielding finger 7-2 and film 7-3 from blank filler panel 7-1.
31. Remove film 9-2 from blank power module panel 9-1.
32. Unscrew the screws on plastic 12-2, and then remove plastic 12-2 from Wire Channel Plate 12-1.
33. Unscrew the screws on Metal Bar 12-3, and then remove Metal Bar 12-3 from Wire Channel Plate 12-1.
34. Remove film 12-4 from Wire Channel Plate 12-1.
35. Unscrew the screws on sheet metal 13-1, and then remove sheet metal 13-1 from fan frame 13-6.
36. Unscrew the screws on fan 13-2, and then remove fan 13-2 from fan frame 13-6.
37. Unscrew the screws on pcb 3, and then remove pcb 13-3 from fan frame 13-6.
38. Unscrew the screws on Fan Plastic Module 13-4, and then remove Fan Plastic Module 13-4 from fan frame 13-6.
39. Remove shielding finger 13-5 from fan frame 13-6.
40. Remove Insulating Plate 17-3 from Mainboard Reinforcing Bar 17-1.
41. Remove movable bushing 17-2 from Mainboard Reinforcing Bar 17-1.

3.2 Optional Graphic. If the disassembly process is complex, insert a graphic illustration below to identify the items contained in the product that require selective treatment (with descriptions and arrows identifying locations).

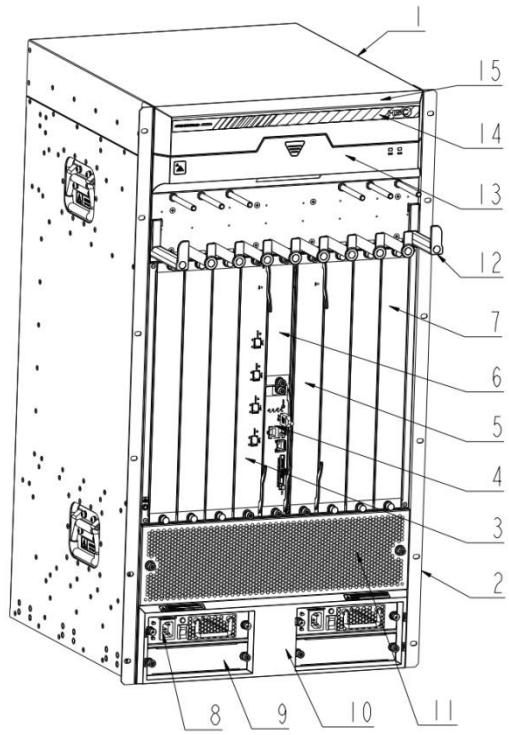


Figure 1 Treatments to the product (front view)

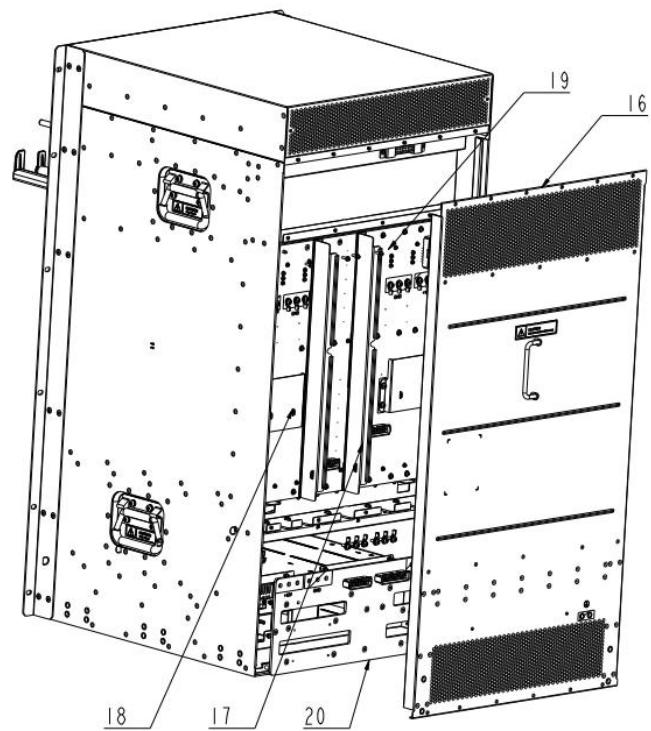


Figure 2 Treatments to the product(rear view)

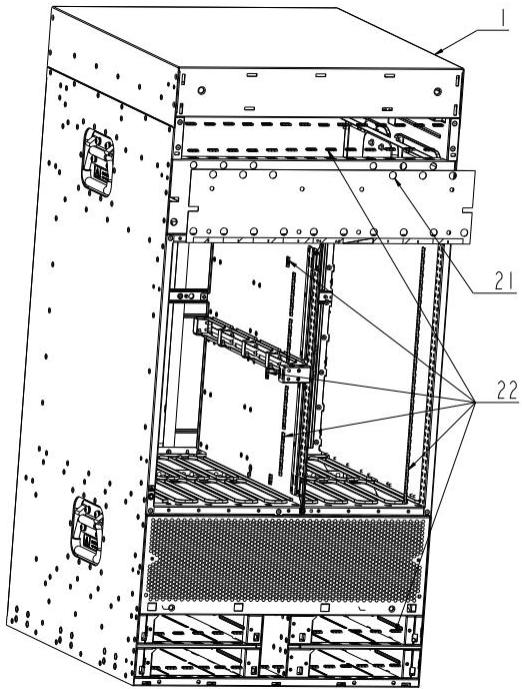


Figure 3 Part 1

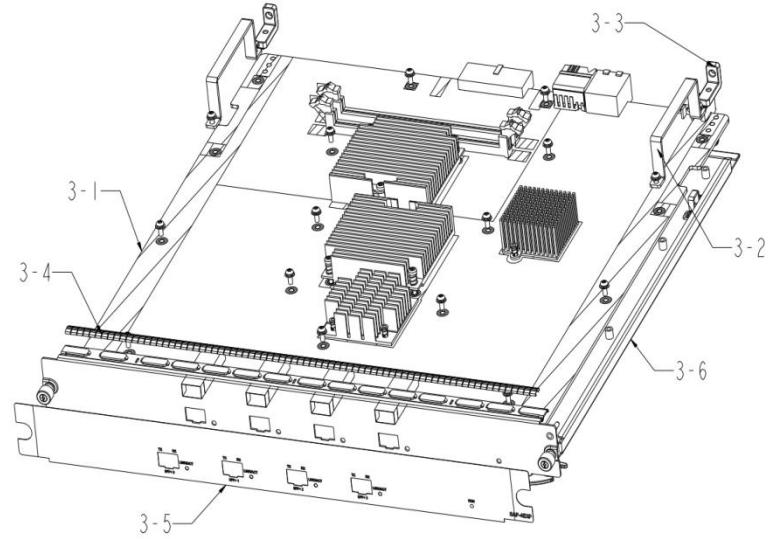


Figure 4 Treatments to front panel 3

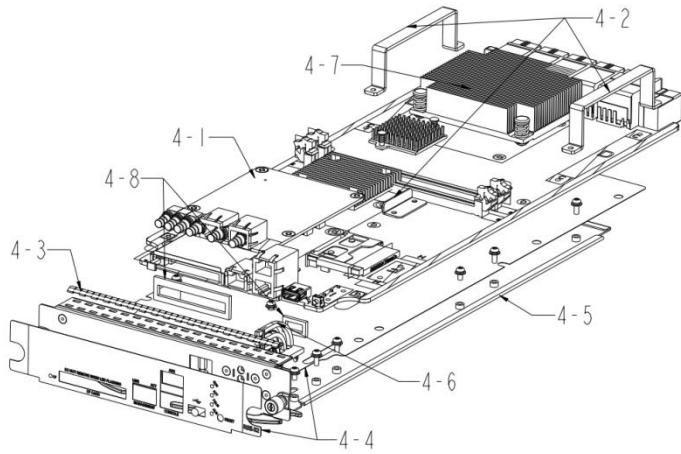


Figure 5 Treatments to front panel 4

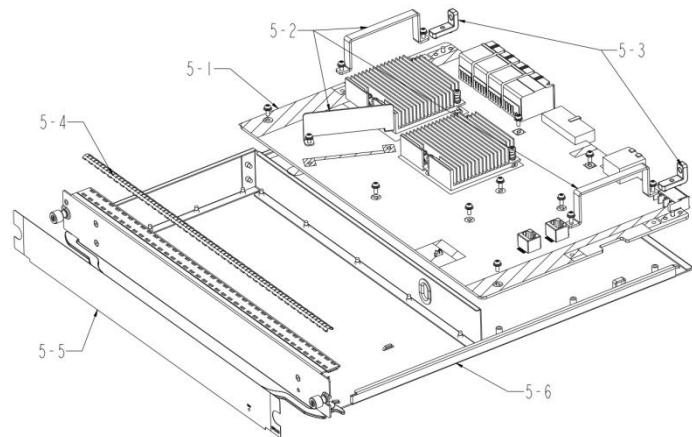


Figure 6 Treatments to blank filler panel 5

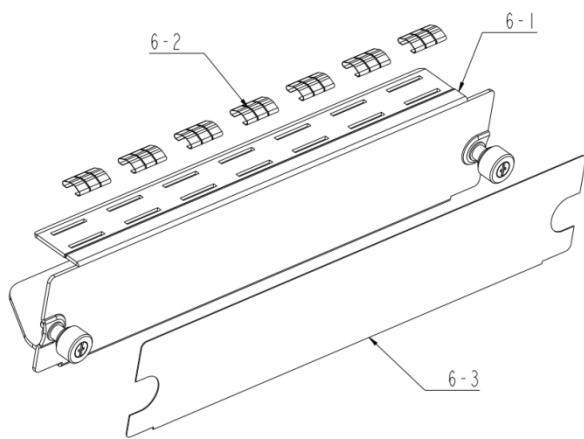


Figure 7 Treatments to blank filler panel 6

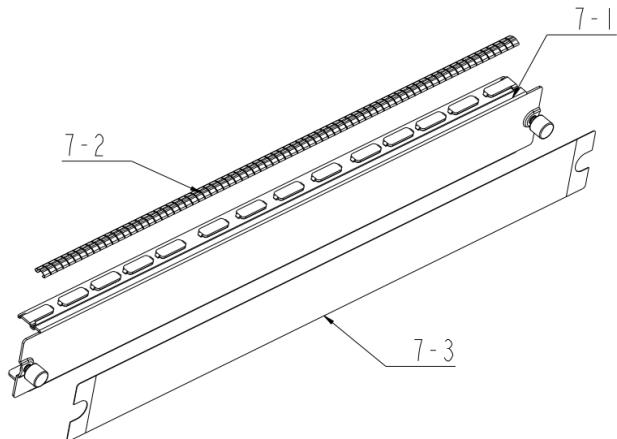


Figure 8 Treatments to blank filler panel 7

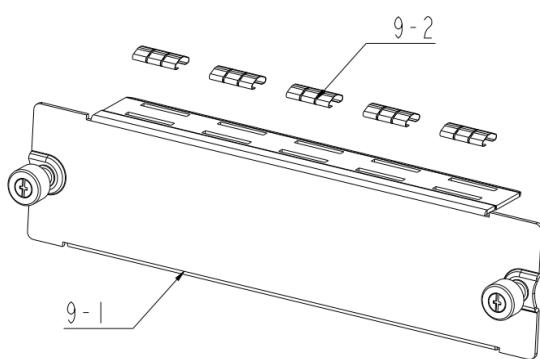


Figure 9 Treatments to blank power module panel 9

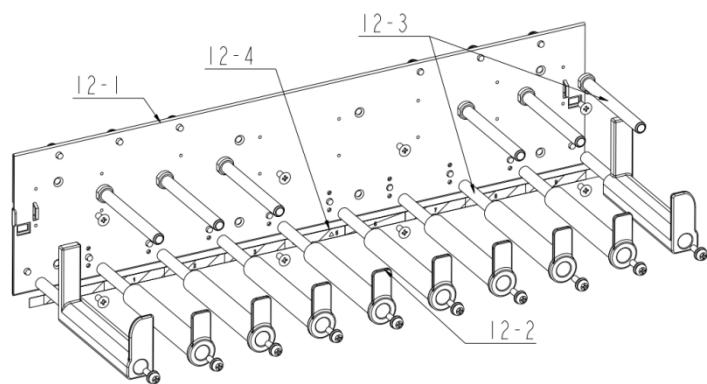


Figure 10 Treatments to Wire Channel 12

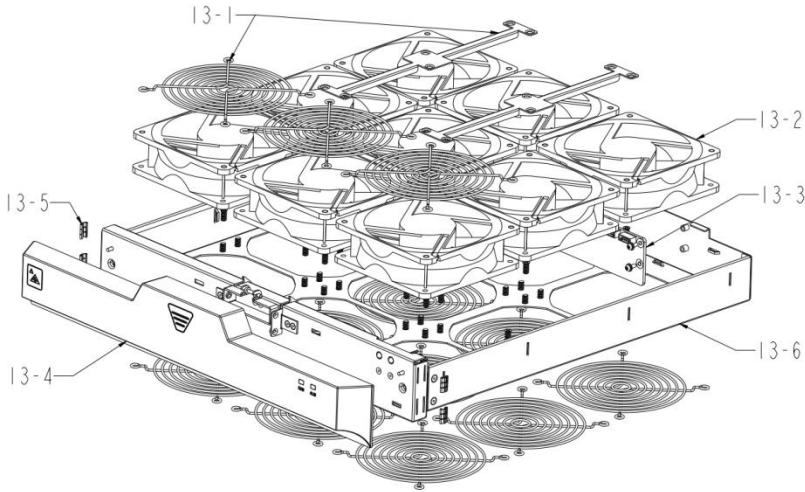


Figure 11 Treatments to fan frame 13

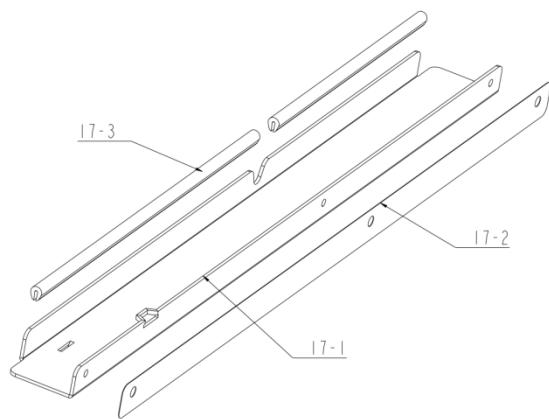


Figure 12 Treatments to Reinforcing Bar 17

3.3 Material of the facility built

| Facility | Components | Material | Weight(g) | Weight percentage | Selective treatment for materials and components | Details |
|----------|------------|-------------|-----------|-------------------|--|---------------|
| 1 | Fe | Fe | 40242 | 55.03% | | Fe recycling |
| 2 | Fe | Fe | 1735 | 2.37% | | Fe recycling |
| 3 | 3-1 | Complex PWB | 1826 | 2.5% | The surface If PCB is greater than 10 square centimeters | |
| | 3-2 | Fe | 38 | 0.05% | | Fe recycling |
| | 3-3 | Al | 9 | 0.012% | | Al recycling |
| | 3-4 | Be-Cu | 4 | 0.005% | | Cu recycling |
| | 3-5 | PC | 6 | 0.008% | | Pla recycling |
| | 3-6 | Fe | 1817 | 2.480% | | Fe recycling |
| 4 | 4-1 | Complex PWB | 815 | 1.11% | The surface If PCB is greater than 10 square centimeters | |
| | 4-2 | Fe | 53 | 0.07% | | Fe recycling |
| | 4-3 | Be-Cu | 1 | 0.001% | | Cu recycling |
| | 4-4 | PC | 3 | 0.004% | | Pla recycling |
| | 4-5 | PC | 15 | 0.02% | | Pla recycling |
| | 4-6 | Fe | 725 | 0.99% | | Fe recycling |
| | 4-7 | PC | 2 | 0.003% | | Pla recycling |
| | 4-8 | AL | 186 | 0.26% | | Al recycling |
| 5 | 5-1 | Complex PWB | 1100 | 1.5% | The surface If PCB is greater than 10 square centimeters | |
| | 5-2 | Fe | 57 | 0.08% | | Fe recycling |
| | 5-3 | Al | 9 | 0.012% | | Al recycling |
| | 5-4 | Be-Cu | 3 | 0.004% | | Cu recycling |
| | 5-5 | PC | 6 | 0.008% | | Pla recycling |
| | 5-6 | Fe | 2069 | 2.83% | | Fe recycling |
| 6 | 6-1 | Fe | 177 | 0.24% | | Fe recycling |

| | | | | | | |
|----|------|-------------|--------|--------|--|---------------|
| | 6-2 | Be-Cu | 1 | 0.001% | | Cu recycling |
| | 6-3 | PC | 3 | 0.004% | | Pla recycling |
| 7 | | | | | | |
| | 7-1 | Fe | 303*6 | 2.490% | | Fe recycling |
| | 7-2 | Be-Cu | 4*6 | 0.030% | | Cu recycling |
| | 7-3 | PC | 6*6 | 0.05% | | Pla recycling |
| | 8 | | 2430*2 | 6.65% | | |
| 9 | | | | | | |
| | 9-1 | Fe | 122*2 | 0.33% | | Fe recycling |
| | 9-2 | Be-Cu | 1*2 | 0.003% | | Cu recycling |
| | 10 | PC/ABS | 127 | 0.17% | | Pla recycling |
| | 11 | Fe | 635 | 0.87% | | Fe recycling |
| 12 | | | | | | |
| | 12-1 | Fe | 786 | 1.1% | | Fe recycling |
| | 12-2 | PC/ABS | 150 | 0.2% | | Fe recycling |
| | 12-3 | Pla | 470 | 0.64% | | Pla recycling |
| | 12-4 | PC | 1 | 0.001% | | Pla recycling |
| 13 | | | | | | |
| | 13-1 | Fe | 553 | 0.76% | | Fe recycling |
| | 13-2 | Pla | 330*9 | 4.06% | | Pla recycling |
| | 13-3 | Complex PWB | 134 | 0.18% | The surface If PCB is greater than 10 square centimeters | Complex PWB |
| | 13-4 | PC/ABS | 190 | 0.26% | | Pla recycling |
| | 13-5 | Be-Cu | 1 | 0.001% | | Cu recycling |
| | 13-6 | Fe | 1452 | 1.99% | | Fe recycling |
| | 14 | PC | 2 | 0.003% | | Pla recycling |
| | 15 | PC/ABS | 158 | 0.220% | | Pla recycling |
| | 16 | Fe | 4220 | 5.770% | | Fe recycling |
| 17 | | | | | | |
| | 17-1 | Fe | 280 | 0.38% | | Fe recycling |
| | 17-2 | PC | 2 | 0.003% | | Pla recycling |
| | 17-3 | Rubber | 9 | 0.012% | | |
| | 18 | Fe | 77 | 0.1% | | Fe recycling |
| | 19 | Complex PWB | 2300 | 3.14% | The surface If PCB is greater than 10 square centimeters | Complex PWB |
| | 20 | Complex PWB | 700 | 0.957% | The surface If PCB is greater than 10 square centimeters | Complex PWB |
| | 21 | PC | 16 | 0.02% | | Pla recycling |
| | 22 | Be-Cu | 13 | 0.018% | | Cu recycling |

4. Revised record

| Date | Version | Author | Modify content |
|------------|---------|--------------|-----------------|
| 2012.10.31 | V0 | Liu Xiaoyuan | Initial version |